

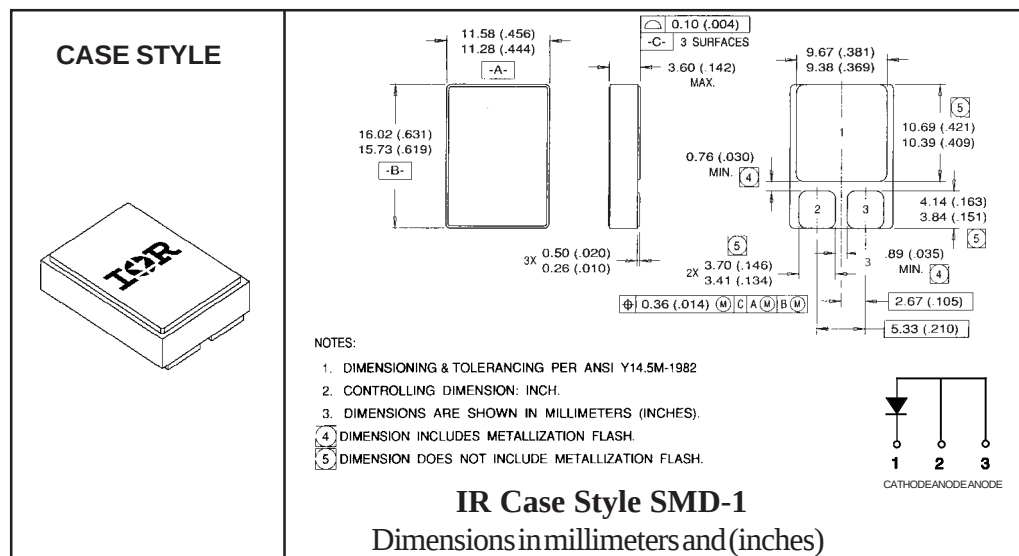
Major Ratings and Characteristics

Characteristics	60LQ045	Units
$I_{F(AV)}$ Rectangular waveform	60	A
V_{RRM}	45	V
I_{FSM} @ $t_p = 8.3ms$ sine	400	A
V_F @ 60Apk, $T_J = 25^\circ C$	0.68	V
T_J, T_{stg} Operating and storage	-55 to 150	$^\circ C$

Description/Features

The 60LQ045 Schottky rectifier has been expressly designed to meet the rigorous requirements of hi -rel environments. It is packaged in the hermetic surface mount SMD-1 ceramic package and has extremely low reverse leakage at high temperature. Full MIL-PRF-19500 quality conformance testing is available on source control drawings to JANTX, JANTXV and S levels. Typical applications include switching power supplies and resonant power converters.

- Hermetically sealed
- Low forward voltage drop
- High frequency operation
- Guard ring for enhanced ruggedness and long term reliability
- Surface Mount
- Lightweight



Voltage Ratings

Part number	60LQ045
V _R Max. DC Reverse Voltage (V)	45
V _{RWM} Max. Working Peak Reverse Voltage (V)	

Absolute Maximum Ratings

Parameters	60LQ045	Units	Conditions
I _{F(AV)} Max. Average Forward Current See Fig. 5	60	A	50% duty cycle @ T _C = 105°C, rectangular waveform ②
I _{FSM} Max. Peak One Cycle Non - Repetitive Surge Current	400	A	@ t _p = 8.3 ms sine ②

Electrical Specifications

Parameters	60LQ045	Units	Conditions
V _{FM} Max. Forward Voltage Drop See Fig. 1 ①	0.51	V	@ 10A
	0.68	V	@ 60A
	0.82	V	@ 120A
	0.69	V	@ 10A
	0.60	V	@ 60A
	0.74	V	@ 120A
I _{RM} Max. Reverse Leakage Current See Fig. 2 ①	0.80	mA	T _J = 25°C
	45	mA	T _J = 125°C
C _T Max. Junction Capacitance	2900	pF	V _R = 5V _{DC} , (100KHz to 1MHz) 25°C ②
L _S Typical Series Inductance	2.8	nH	Measured from center of bond pad to end of anode bonding wire

Thermal-Mechanical Specifications

Parameters	60LQ045	Units	Conditions
T _J Max. Junction Temperature Range	-55 to 150	°C	
T _{stg} Max. Storage Temperature Range	-55 to 150	°C	
R _{thJC} Max. Thermal Resistance, Junction to Case	1.0	°C/W	DC operation See Fig. 4
R _{thJC} Max. Thermal Resistance, Junction to case (Per Package)	0.50	°C/W	DC operation
w _t Weight (Typical)	2.6	g	
Die Description (Square)	0.200	inches	
Case Style	SMD-1		

① Pulse Width < 300μs, Duty Cycle < 2%

② Pins 2 and 3 externally tied together

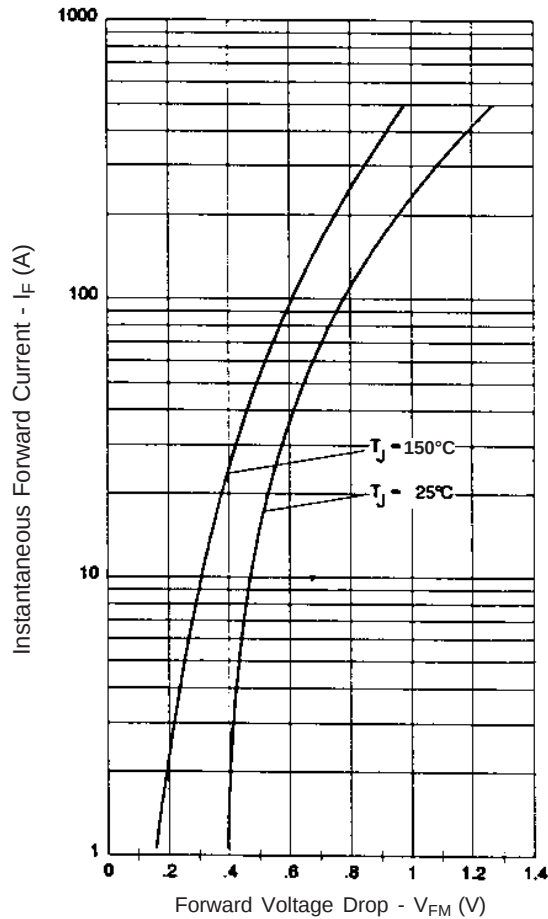


Fig. 1 - Max. Forward Voltage Drop Characteristics

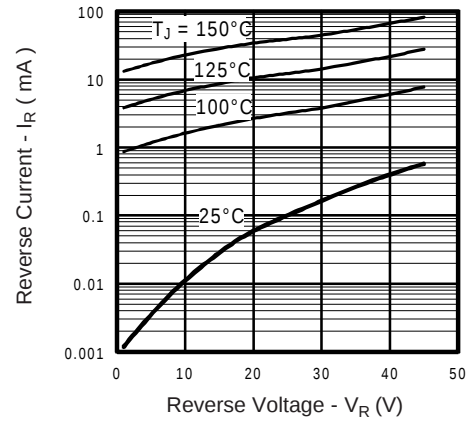


Fig. 2 - Typical Values of Reverse Current Vs. Reverse Voltage

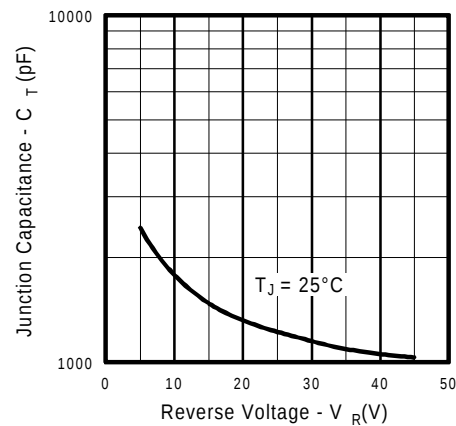


Fig. 3 - Typical Junction Capacitance Vs. Reverse Voltage

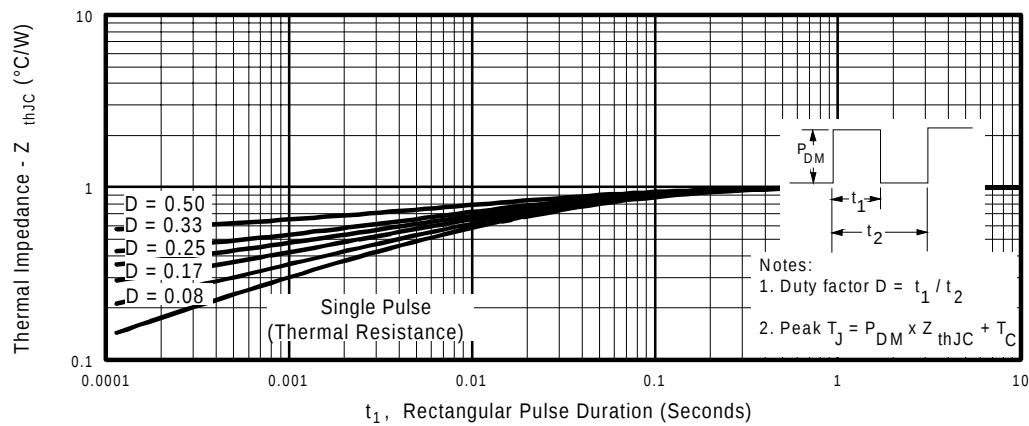


Fig. 4 - Max. Thermal Impedance Z_{thJC} Characteristics

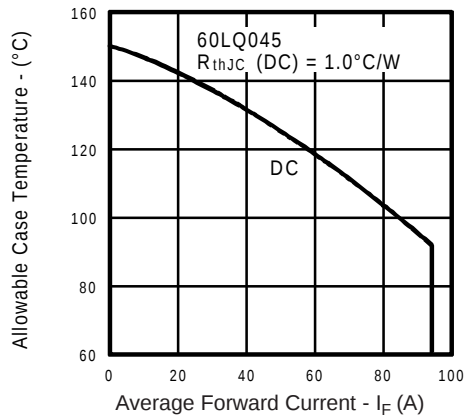


Fig. 5 - Max. Allowable Case Temperature Vs. Average Forward Current

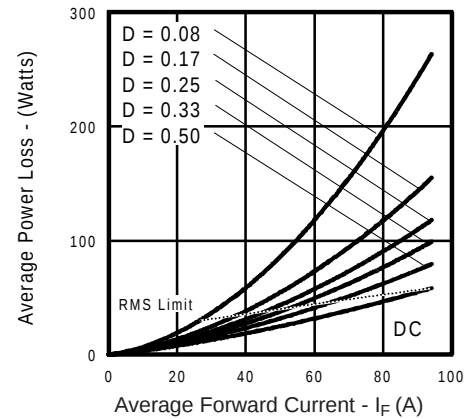


Fig. 6 - Forward Power Loss Characteristics